



Material Content Data Sheet



Sales Product Name		BSC060N10NS3 G		Issued		31. July 2018		
MA#		MA001638048						
Package		PG-TDSON-8-39		Weight*		114.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.423	3.87	3.87	38713	38713
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	iron	7439-89-6	0.049	0.04		426	
	non noble metal	copper	7440-50-8	48.649	42.59	42.64	425807	426361
	non noble metal	copper	7440-50-8	0.057	0.05	0.05	501	501
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	501	501
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		679	
	plastics	epoxy resin	-	6.133	5.37		53677	
	inorganic material	silicondioxide	60676-86-0	32.605	28.54	33.98	285374	339730
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13304	13304
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1387	1387
solder	non noble metal	tin	7440-31-5	0.070	0.06		610	
	noble metal	silver	7440-22-4	0.087	0.08		762	
	non noble metal	lead	7439-92-1	3.327	2.91	3.05	29120	30492
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1313	
	non noble metal	copper	7440-50-8	16.910	14.80	14.94	148007	149512
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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